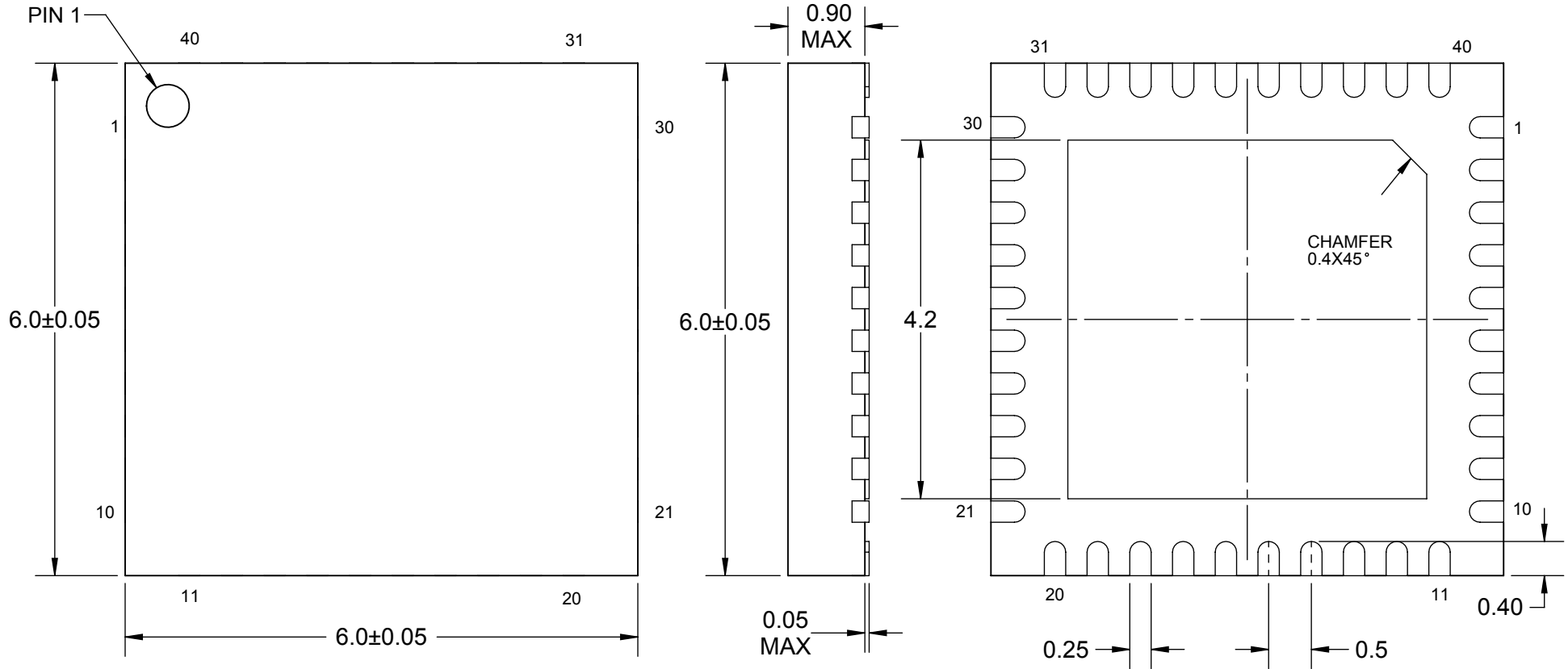


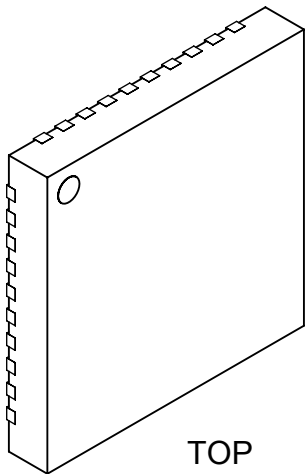
# HCD J9K

# G89 J9K

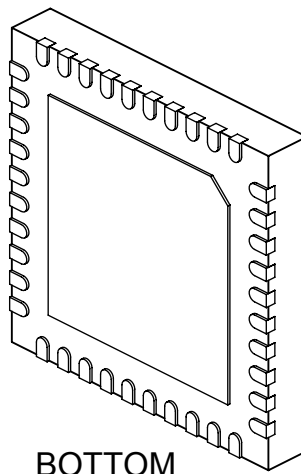
# 6CHCA J9K



## MODEL



TOP



BOTTOM

### Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: Ni Pd Au.
- 4) FRAME THICKNESS: 0.203mm.
- 5) DIE PAD: 4.2 x 4.2mm EXPOSED BOTTOM.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS mm.

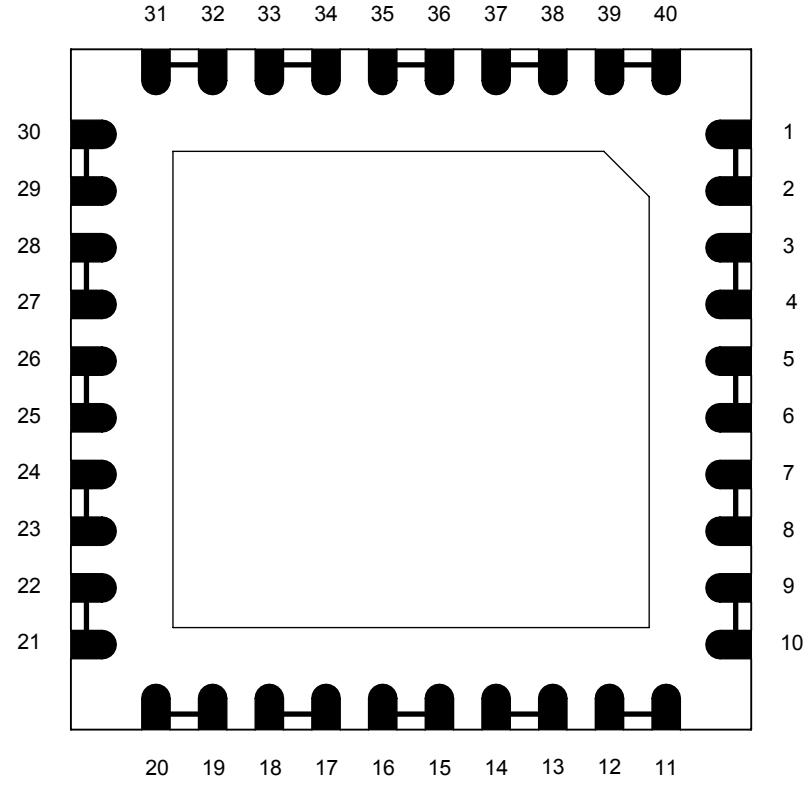
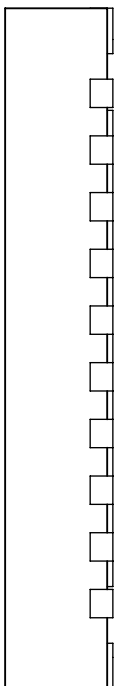
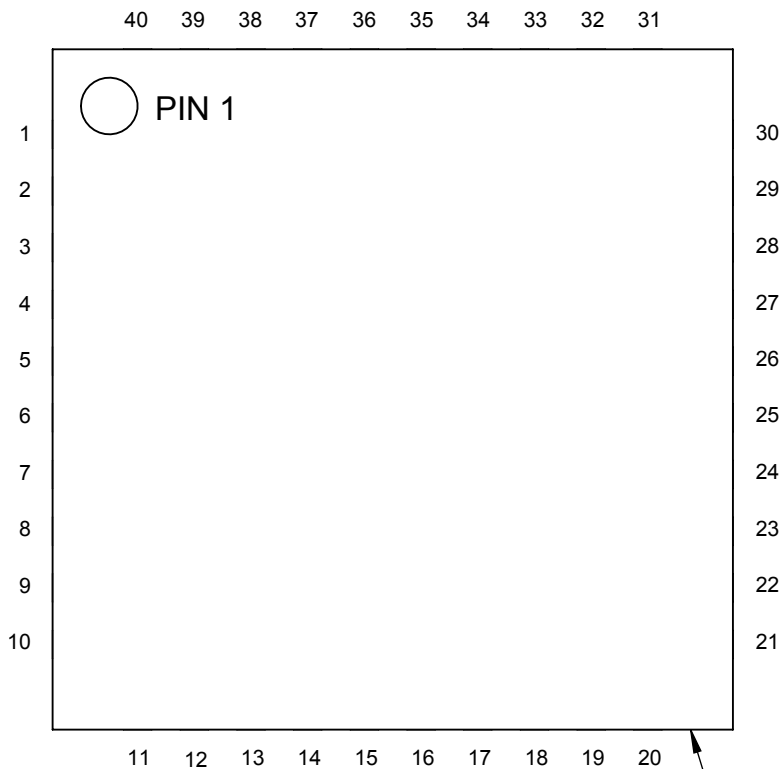
APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	4/30/2020				
ENG M. Hart	4/30/2020	TITLE 40-LEAD 6mm P0.5mm QFN DAISY CHAIN			
MFG		SCALE 15:1	SIZE A	DRAWING NO. 454042	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 5
CUST					
REVISED					

'D5 8 'D5 HH9 F B

HCD'J-9K

G-89'J-9K

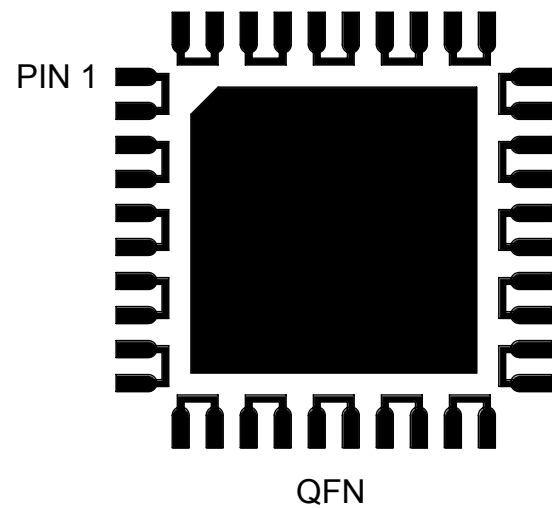
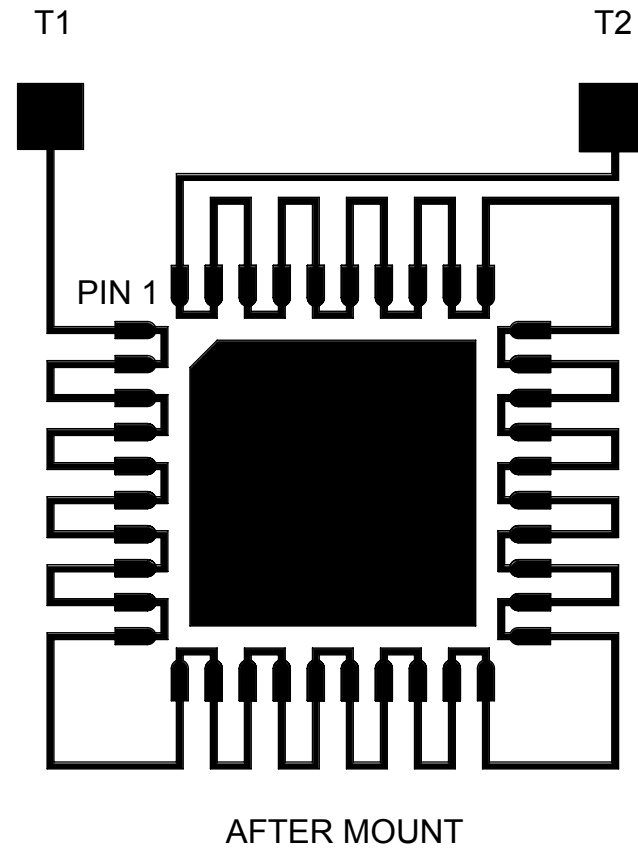
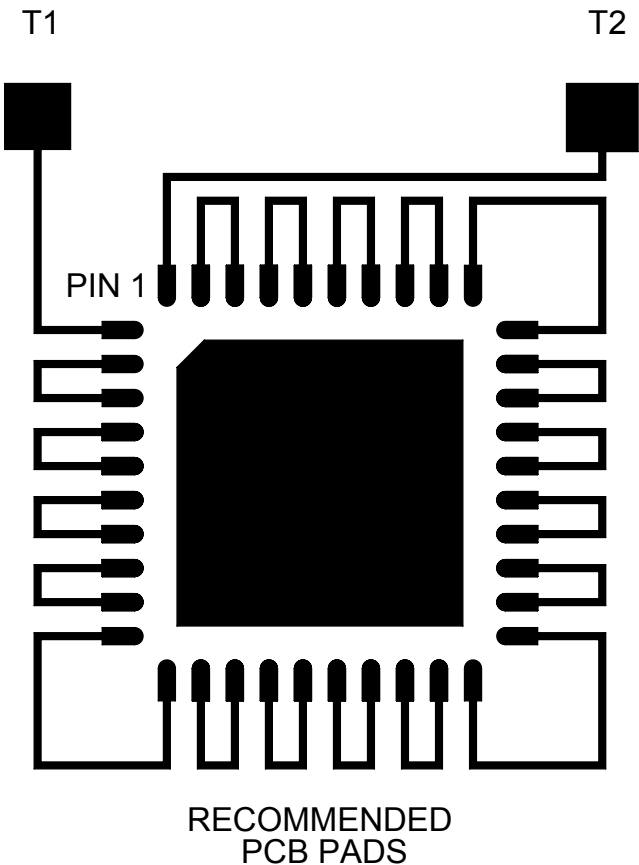
6 CHHCA 'J-9K



TOP SIDE  
ENCAPSULATION

NOTE:  
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS

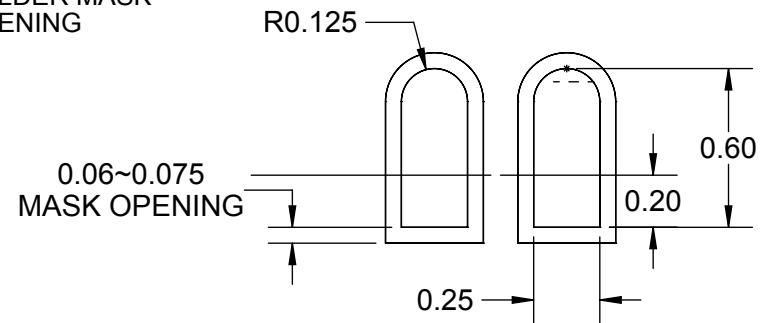
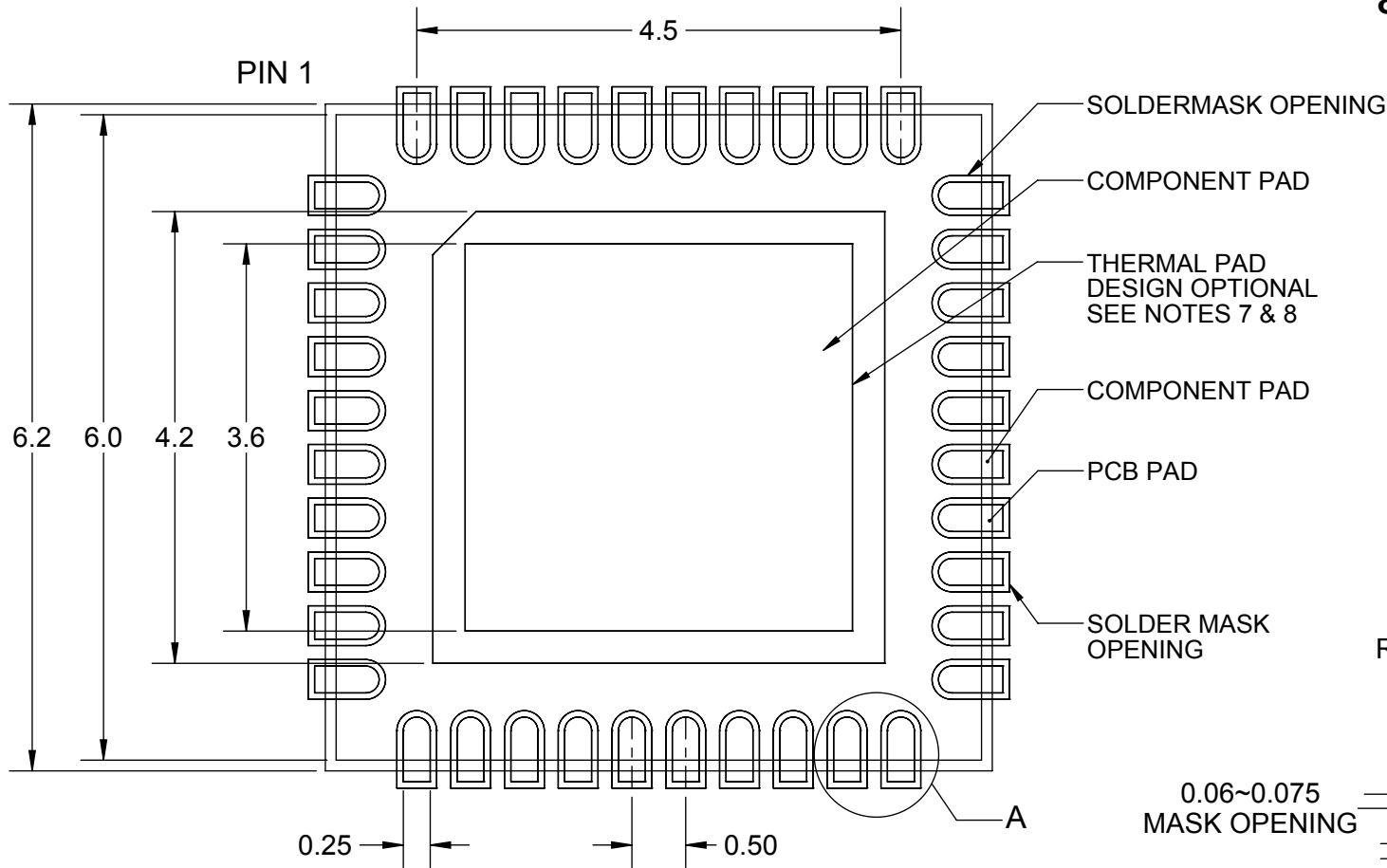
<b>TopLine®</b>			
TITLE    40-LEAD 6mm P0.5mm QFN DAISY CHAIN			
SCALE 15:1	SIZE A	DRAWING NO. 454042	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 5



85±GM7<5±B B9H@GH		
PINS	PINS	PINS
1 ~ 2	3 ~ 4	5 ~ 6
7 ~ 8	9 ~ 10	11 ~ 12
13 ~ 14	15 ~ 16	17 ~ 18
19 ~ 20	21 ~ 22	23 ~ 24
25 ~ 26	27 ~ 28	29 ~ 30
31 ~ 32	33 ~ 34	35 ~ 36
37 ~ 38	39 ~ 40	

TITLE 40-LEAD 6mm P0.5mm QFN DAISY CHAIN			
SCALE 9:1	SIZE A	DRAWING NO. 454042	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 5

D7 '6 C5 F8 ' @ MCI H  
 8 -A9BG-CBG-B'AA  
 J-9K : FCA'HCD



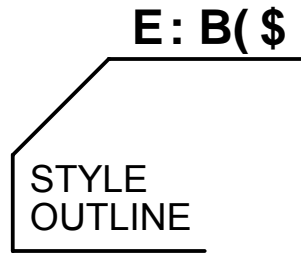
DETAIL A  
 SCALE 35 : 1

Notes: (Unless Otherwise Specified).

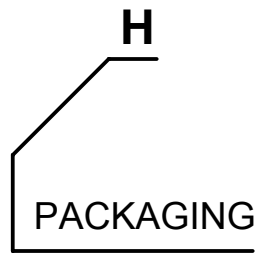
- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
  - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
  - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
  - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
  - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
  - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
  - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
  - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

<b>TopLine®</b>			
TITLE		40-LEAD 6mm P0.5mm QFN DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
15:1	A	454042	A
DO NOT SCALE DRAWING			SHEET 4 OF 5

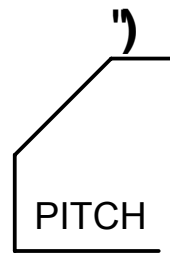
**D5FHBI A69F-B; GMGH9A**



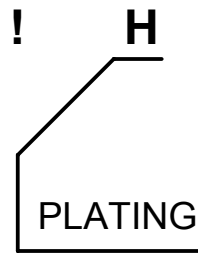
QUAD FLAT  
NO LEAD  
40 PIN



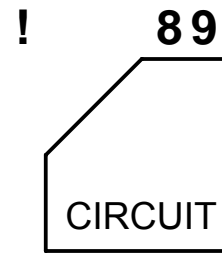
T = TRAY  
M = TUBE  
E = CUT TAPE  
E7A = 7" REEL



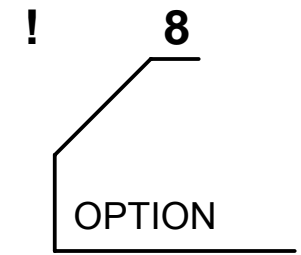
.5 = 0.5MM



F = NiPdAu  
T = Sn100 Tin



DE = DAISY CHAIN  
ISO = ISOLATED  
BLANK = DUMMY



BLANK = NONE  
D = DUMMY DIE

<b>D5FHBI A69F</b>	<b>7F7I #</b>	<b>D57?5; #;</b>	<b>Fc&lt;G DVI: F99</b>	<b>AG@ @J9@</b>	<b>8I AAM 89</b>
QFN40T.5-T-DE-D	DAISY CHAIN	JEDEC TRAY	YES	Sn100	YES
QFN40M.5-T-DE-D	DAISY CHAIN	TUBE	YES	Sn100	YES
QFN40E.5-T-DE-D	DAISY CHAIN	TAPE & REEL	YES	Sn100	YES
QFN40T.5-T-ISO	ISOLATED	JEDEC TRAY	YES	Sn100	NO
QFN40M.5-T-ISO	ISOLATED	TUBE	YES	Sn100	NO
QFN40E.5-T-ISO	ISOLATED	TAPE & REEL	YES	Sn100	NO
QFN40T.5-T-D	DUMMY	JEDEC TRAY	YES	Sn100	YES
QFN40M.5-T-D	DUMMY	TUBE	YES	Sn100	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

<b>TopLine®</b>			
TITLE 40-LEAD 6mm P0.5mm QFN DAISY CHAIN			
SCALE NONE	SIZE A	DRAWING NO. 454042	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 5